QUALITY SEMICONDUCTOR, INC.

High Speed CMOS 3.3V 16-Bit Bus Register Transceiver

QS74LCX16952

FEATURES/BENEFITS

- 5V tolerant inputs and outputs
- Industry standard pinouts
- 10µA I_{CCQ} quiescent power supply current
- Hot insertable
- 2.0V – 3.6V V_{CC} supply operation
- ±24mA balanced output drive
- Meets or exceeds JEDEC Standard 36 specifications
- t_{PD} = 6.3ns
- Input hysteresis for noise immunity
- Multiple power and ground pins for low noise
- Operating temperature range: –40°C to +85°C
- Latch-up performance exceeds 500mA
- ESD performance:
  - Human body model > 2000V
  - Machine model > 200V
- Packages available:
  - 56-pin TSSOP
  - 56-pin SSOP

DESCRIPTION

The LCX16952 is a 16-bit bus register transceiver with three-state outputs that is ideal for driving address and data buses. Two independent 8-bit registered transceivers are used to permit independent control of data flow in either direction. The 3.3V LCX family features low power, low switching noise, and fast switching speeds for low power portable applications as well as high-end advanced workstation applications. 5V tolerant inputs and outputs allow this LCX product to be used in mixed 5V and 3.3V systems. Easy board layout is facilitated by the use of flow-through pinouts and byte enable controls provide architectural flexibility for systems designers. To accommodate hot-plug or live insertion applications, this product is designed not to load an active bus when V_{CC} is removed.

Figure 1. Functional Block Diagram

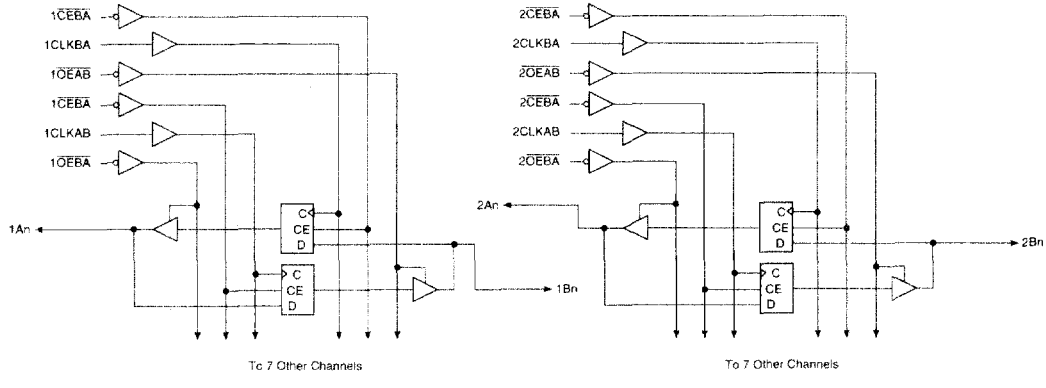


Figure 2. Pin Configuration

(All Pins Top View)

SSOP, TSSOP

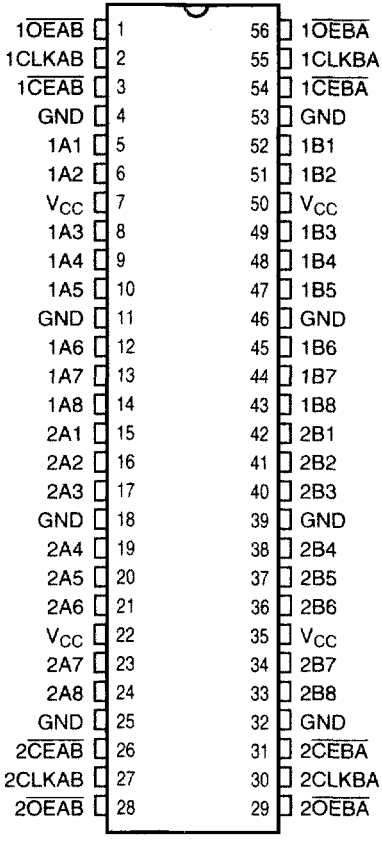


Table 1. Pin Description

Name	Description
$x\overline{OEAB}$	A to B Output Enable Inputs (Active LOW)
$x\overline{OEBA}$	B to A Output Enable Inputs (Active LOW)
$x\overline{CEAB}$	A to B Enable Inputs (Active LOW)
$x\overline{CEBA}$	B to A Enable Inputs (Active LOW)
xCLKAB	A to B Clock Inputs
xCLKBA	B to A Clock Inputs
xAx	A to B Data Inputs or B to A 3-State Outputs
xBx	B to A Data Inputs or A to B 3-State Outputs

3

Table 2. Function Table (1, 2)

Inputs				Outputs
$x\overline{CEAB}$	xCLKAB	$x\overline{OEAB}$	xAx	xBx
H	X	L	X	B(3)
X	L	L	X	B(3)
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

Notes:

1. ↑ = LOW-to-HIGH Transition
   H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
2. A-to-B data flow shown: B-to-A flow control is the same, except using $x\overline{CEBA}$, xCLKBA, and $x\overline{OEBA}$.
3. Level of B before the indicated steady-state input conditions were established.

Table 3. Capacitance

Symbol	Pins	Typ	Unit	Conditions
C_{IN}	Input Capacitance	7.0	pF	V_{IN} = 0V, V_{OUT} = 0V, f = 1MHz
$C_{I/O}$	I/O Capacitance	8.0	pF	V_{IN} = 0V, V_{OUT} = 0V, f = 1MHz
C_{PD}	Power Dissipation Capacitance	25	pF	V_{CC} = 3.3V, V_{IN} = 0 or V_{CC}, f = 10MHz

Note: Capacitance is characterized but not production tested.

Table 4. Absolute Maximum Ratings

Supply Voltage to Ground	–0.5V to +7.0V
DC Output Voltage V_{OUT}	
Outputs HIGH-Z	–0.5V to +7.0V
Outputs Active	–0.5V to V_{CC} +0.5V
DC Input Voltage V_{IN}	–0.5V to +7.0V
DC Input Diode Current with $V_{IN} < 0$	–50mA
DC Output Diode Current	
$V_O < 0$	–50mA
$V_O > V_{CC}$	+50mA
DC Output Source/Sink Current (I_{OH}/I_{OL})	±50mA
DC Supply Current per Supply Pin	±100mA
DC Ground Current per Ground Pin	±100mA
T_{STG} Storage Temperature	–65° to +150°C

Note: Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to this device resulting in functional or reliability type failures.

Table 5. Recommended Operating Conditions

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage, Operating		2.0	3.6	V
	Supply Voltage, Data Retention		1.5	3.6	
V_{IN}	Input Voltage		0	5.5	V
V_{OUT}	Output Voltage in Active State		0	V_{CC}	V
	Output Voltage in "OFF" State		0	5.5	
I_{OH}/I_{OL}	Output Current	V_{CC} = 3.0 – 3.6V	—	±24	mA
		V_{CC} = 2.7V	—	±12	
$\Delta t/\Delta v$	Input Transition Slew Rate		—	10	ns/V
T_A	Operating Free Air Temperature		–40	+85	°C

Table 6. DC Electrical Characteristics Over Operating Range

Industrial Temperature Range, $T_A = -40°C$ to $+85°C$.

Symbol	Parameter	Test Conditions	Min	Typ[1]	Max	Unit
V_{IH}	Input HIGH Voltage	Logic HIGH for All Inputs	2.0	—	—	V
V_{IL}	Input LOW Voltage	Logic LOW for All Inputs	—	—	0.8	V
V_{OH}	Output HIGH Voltage	V_{CC} = 2.7V, I_{OH} = −100µA V_{CC} = 2.7V, I_{OH} = −12mA V_{CC} = 3.0V, I_{OH} = −18mA V_{CC} = 3.0V, I_{OH} = −24mA	V_{CC} −0.2 2.2 2.4 2.2	— — — —	— — — —	V
V_{OL}	Output LOW Voltage	V_{CC} = 2.7V, I_{OL} = 100µA V_{CC} = 2.7V, I_{OL} = 12mA V_{CC} = 3.0V, I_{OL} = 16mA V_{CC} = 3.0V, I_{OL} = 24mA	— — — —	— — — —	0.2 0.4 0.4 0.5	V
ΔV_T	Input Hysteresis[2]	$V_{TLH} - V_{THL}$ for All Inputs	—	150	—	mV
I_I	Input Leakage Current	V_{CC} = Max., V_I = 0V, V_I = 5.5V	—	—	±1.0	µA
I_{OZ}	High-Z I/O Leakage	V_{CC} = Max., $V_I = V_{IH}$ or V_{IL}, V_O = 0V, V_O = 5.5V	—	—	±1.0	µA
I_{OFF}	Power Off Leakage	V_{CC} = 0V, V_I or V_O = 5.5V	—	—	10	µA
I_{OS}	Short Circuit Current[2,3]	V_{CC} = 3.6V, V_{OUT} = GND	−60	—	−240	mA
V_{IK}	Input Clamp Voltage	V_{CC} = 2.7V, I_{IN} = −18mA	—	−0.7	−1.2	V

Notes:
1. Typical values indicate V_{CC} = 3.3V, and T_A = 25°C.
2. These parameters are guaranteed by characterization, but not production tested.
3. Not more than one output should be tested at one time. Duration of test should not exceed one second.

Table 7. Power Supply Characteristics

Symbol	Parameter	Test Conditions[1]		Typ[1]	Max	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC} = 3.6V, Freq = 0, V_{IN} = GND or V_{CC}		0.1	10	µA
ΔI_{CC}	Supply Current per Input @ TTL HIGH	V_{CC} = 3.6V, V_{IN} = V_{CC} –0.6V		2.0	30	µA
I_{CCD}	Supply Current per Input per MHz[4]	V_{CC} = 3.6V, Outputs Open One Bit Toggling @ 50% Duty Cycling $x\overline{OEAB}$ = $x\overline{CEAB}$ = GND $x\overline{OEBA}$ = V_{CC}	V_{IN} = V_{CC} V_{IN} = GND	65	100	µA/ MHz
I_C	Total Power Supply Current[6]	V_{CC} = 3.6V, Outputs Open One Bit Toggling @ 50% Duty Cycle f = 5MHz, f_{CP} = 10MHz (xCLKAB) $x\overline{OEAB}$ = $x\overline{CEAB}$ = GND $x\overline{OEBA}$ = V_{CC}	V_{IN} = V_{CC} –0.6V V_{IN} = GND	0.7[5]	1.05[5]	mA
		V_{CC} = 3.6V, Outputs Open Sixteen Bits Toggling @ 50% Duty Cycling f = 2.5MHz, f_{CP} = 10MHz (xCLKAB) $x\overline{OEAB}$ = $x\overline{CEAB}$ = GND $x\overline{OEBA}$ = V_{CC}	V_{IN} = V_{CC} –0.6V V_{IN} = GND	2.7[5]	4.3[5]	mA

Notes:
1. For conditions shown as Min. or Max. use the appropriate value specified under Recommended Operating Conditions for the applicable device type.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.
3. Per TTL driven input. All other inputs at V_{CC} or GND.
4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed by design but not tested.
6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$.
   $I_C = I_{CCQ} + \Delta I_{CC} D_H N_T + I_{CCD} f N_O$.
   I_{CCQ} = Quiescent Current (I_{CCL}, I_{CCH}, and I_{CCZ}).
   ΔI_{CC} = Power Supply Current for a TTL-High Input (V_{IN} = V_{CC} –0.6V).
   D_H = Duty Cycle for TTL High Inputs.
   N_T = Number of TTL High Inputs.
   I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL).
   f = Average Switching Frequency per Output.
   N_O = Number of Outputs Switching.

Table 8. Dynamic Switching Characteristics[1]

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = 25°C Typical	Units
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V	3.3	0.8	V
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V	3.3	0.8	V

Note: 1. Characterized but not production tested.

Table 9. Switching Characteristics Over Operating Range

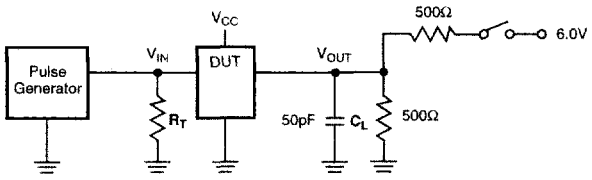
Industrial Temperature Range, $T_A = -40°C$ to $+85°C$.
$C_{LOAD} = 50pF$, $R_{LOAD} = 500\Omega$ unless otherwise noted.

Symbol	Description[1]	LCX16952				Unit
		$V_{CC} = 3.3 \pm 0.3V$		$V_{CC} = 2.7V$[2]		
		Min	Max	Min	Max	
t_{PHL} t_{PLH}	Propagation Delay xCLKAB, xCLKBA to xAx, xBx	2.0	6.3	2.0	7.3	ns
t_{PZH} t_{PZL}	Output Enable Time $x\overline{OEBA}$, $x\overline{OEAB}$ to xAx, xBx	1.5	7.0	1.5	8.0	ns
t_{PHZ} t_{PLZ}	Output Disable Time[2] $x\overline{OEBA}$, $x\overline{OEAB}$ to xAx, xBx	1.5	6.5	1.5	7.5	ns
t_{SU}	Setup Time HIGH or LOW xAx, xBx to xCKLAB, xCKLBA	2.5	—	2.5	—	ns
t_H	Hold Time HIGH or LOW xAx, xBx to xCLKAB, xCLKBA	1.5	—	1.5	—	ns
t_{SU}	Setup Time HIGH or LOW $x\overline{CEBA}$, $x\overline{CEAB}$ to xCLKAB, xCLKBA	3.0	—	3.0	—	ns
t_H	Setup Time HIGH or LOW $x\overline{CEBA}$, $x\overline{CEAB}$ to xCLKAB, xCLKBA	2.0	—	2.0	—	ns
t_W	Pulse Width LOW xCLKAB to xCLKBA[2]	3.0	—	3.0	—	ns
$t_{SK(O)}$	Output Skew[3]	—	0.5	—	—	ns

Notes:
1. Minimums guaranteed but not tested on propagation delays. See Test Circuit and Waveforms.
2. Guaranteed by characterization but not production tested.
3. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by characterization but not production tested.

TEST CIRCUIT AND WAVEFORMS

Figure 3. Test Circuit



SWITCH POSITION

Test	Switch
Open Drain Disable LOW Enable LOW	6V
Disable HIGH Enable HIGH	GND
All Other Inputs	Open

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse generator.

Figure 4. Setup, Hold, and Release Timing

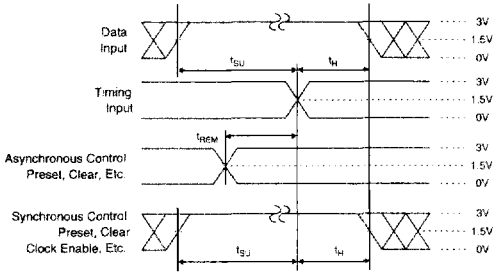


Figure 6. Pulse Width

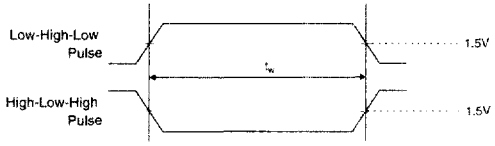


Figure 5. Enable and Disable Timing

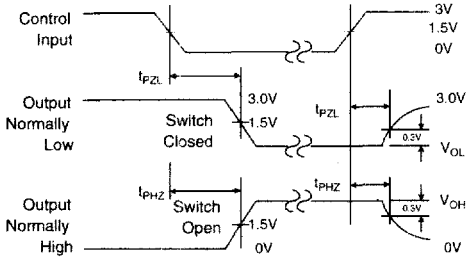
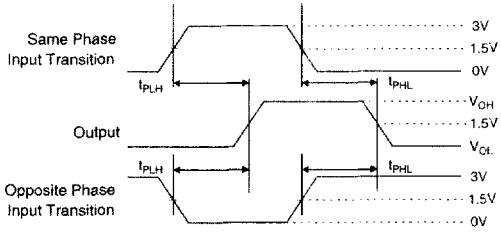


Figure 7. Propagation Delay



Notes:
1. Input Control Enable = LOW and input Control Disable = HIGH.
2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; Z_{OUT} ≤ 50Ω; t_F, t_R ≤ 2.5ns.